

5350

Manual Heavy Wire Bonder

Our new **manual bonder 5350 for heavy wire** is ideally suited for R&D labs, prototype and pilot production and repair facilities who only have limited budgets but need highest bond quality.

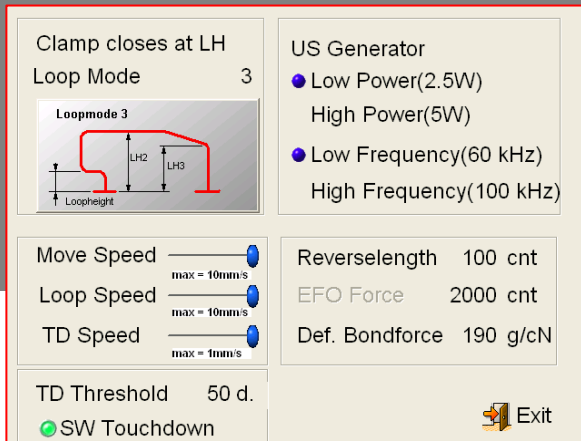
Its most outstanding feature is a full-blown **automatic wire cutting unit** which guarantees perfectly reproducible wire cuts at single-micron precision without any risk of component damage. Thanks to a **motorized Y-axis** of 25 mm travel in addition to the motorized Z axis, it also offers perfectly **identical bond tails** through a programmable, automatic step-back.

Bond tools are identical to those used on fully automatic wire bonders from F&K Delvotec: bond wedges of 2" length, permit access even to **large and deep housings** used in automotive electronics. The patented **self-adjusting wire guides** make changing wire sizes literally a snap.

Even **complicated loop forms** including **reverse loops** or **stitch bonds** are easily executed with minimum operator influence. Uncommonly for a manual bonder, all parameters are programmed and saved on the internal hard disk, supported by a large **LCD colour display** and our popular **shuttle wheel** which is quick and intuitive to handle.

The 5350 software boasts several operating modes from a **fully manual** step-by-step mode to a **production mode** where the operator only has to move to the bond positions and then pushes a single button. Only a **minimum of training** is required.

Hard- and software of the 5350 are very similar to the 5310, 5330 and 53XX BDA thin-wire bonders from the 5300 family. This keeps training and maintenance cost extremely low. At the same time, the bond head is almost identical to that of the fully automatic bonders from F&S BONDTEC, ensuring bonds of the **highest quality** and making **scale-up** to larger production volumes trouble-free.



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Bond System

<i>Wire types</i>	Aluminium wire 100 ... 500 µm and Copper wire 100...300µm on 4" spool
<i>Bond head</i>	Wedge-wedge for heavy wire Standard wedges of 2" length 90° wire guide with patented self-adjusting quick-change wireguide and quick-change cutter Bond force programmable 100 to 1800 cN; voice-coil bond force system
<i>Ultrasonic System</i>	proprietary 60 kHz system
<i>Mechanics</i>	Programmable linear Z-axis with 60 mm travel; step resolution 1 µm Programmable linear Y-axis with 25 mm travel; step resolution 2 µm
Control System	
<i>Hardware</i>	Single-board PC with Windows operating system TFT color display 10,4" (640x480 pixel) simple and rapid operation and programming through shuttle-wheel with push-button
<i>Control modes</i>	manual, semi-auto production mode program line-step for testing
<i>Loop types</i>	Standard rectangular, reverse, stitch, all programmable
Substrate Handling	
<i>Manipulator</i>	in X and Y, working range 18x18 mm stepdown reduction 1:7
<i>Substrate holder</i>	standard 80 mm Ø for parts up to 2"x2" optionally 4"x4" and 95 mm Ø, also with vacuum
General	
<i>Dimensions</i>	Width 630 mm, depth 580 mm; height 400 mm, weight ca. 40 kg
<i>Supplies</i>	100...240 VAC, single-phase, 50/60 Hz, max. 230 VA Ø 6mm standard vacuum tubing

F&S BONDTEC Semiconductor GmbH
 Industriezeile 49a
 5280 Braunau am Inn, Austria
 Tel.: +43-7722-67052-8270
 Fax: +43-7722-67052-8272
 Email: info@fsbondtec.at
 Internet: www.fsbondtec.at